

1A Avg.

200 Volts

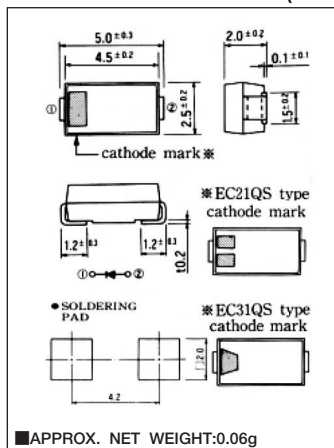
FRED

EC10UA20

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	400	V
平均整流電流 Average Rectified Forward Current	$I_O$	50Hz, 正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	1.0 0.7
実効順電流 R.M.S. Forward Current	$I_F(RMS)$		1.57
サージ順電流 Surge Forward Current	$I_{FSM}$	50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	20
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$		-40~+150
保存温度範囲 Storage Temperature Range	$T_{stg}$		-40~+150

OUTLINE DRAWING(mm)



APPROX. NET WEIGHT:0.06g

電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$	—	—	20	$\mu A$
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$T_j=25^{\circ}C, I_{FM}=1A$	—	0.93	1.10	V
逆回復時間 Reverse Recovery Time	$t_{rr}$	$I_{FM}=1A, -di/dt=50 A/\mu s, T_j=25^{\circ}C$	—	12	20	ns
熱抵抗 Thermal Resistance	抗 $R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	アルミナ基板実装*1		108	$^{\circ}C/W$
			プリント基板実装*2		157	$^{\circ}C/W$

\*1:アルミナ基板実装/Alumina Substrate mounted (Soldering Lands=2×2mm, Both Sides)  
\*2:プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands=2×2mm, Both Sides)

定格・特性曲線

